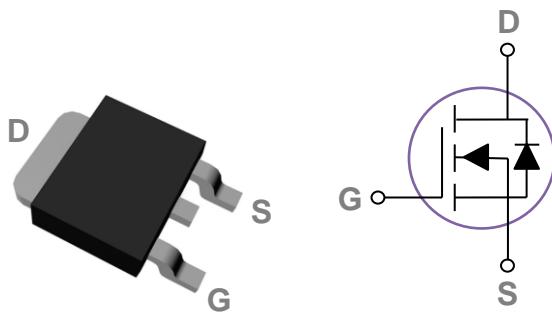


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO252 Pin Configuration



BVDSS	RDS(ON)	ID
80V	4mΩ	120A

### Features

- 80V, 120A,  $RDS(ON) = 4m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	80	V
$V_{GS}$	Gate-Source Voltage	+20/-12	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	120	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	77	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	480	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	400	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	90	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	133	W
	Power Dissipation – Derate above 25°C	1.06	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.94	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	80	---	---	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=64\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	100	$\text{nA}$

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$	---	3.3	4	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	2	3	4	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=5\text{A}$	---	18	---	S

**Dynamic and switching Characteristics**

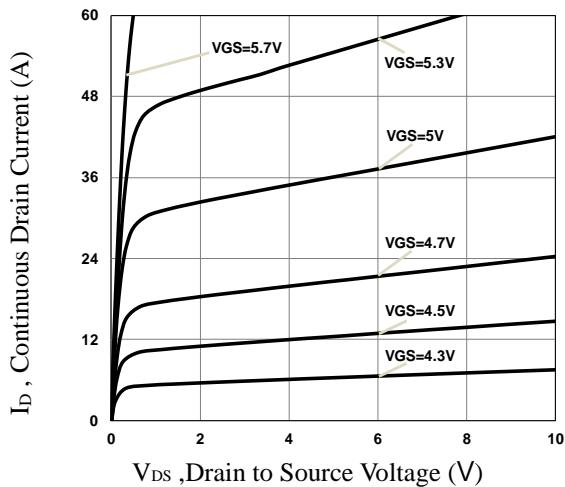
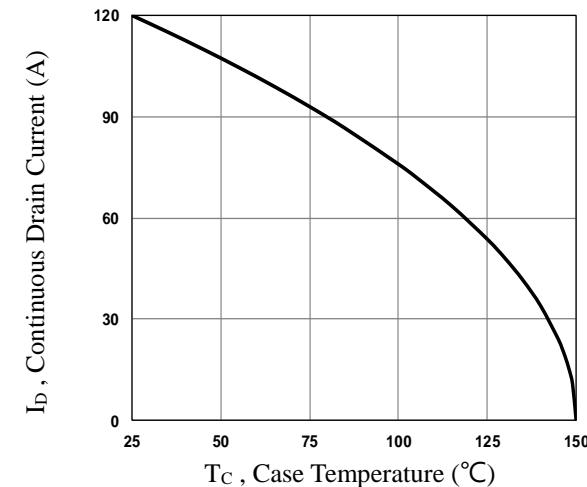
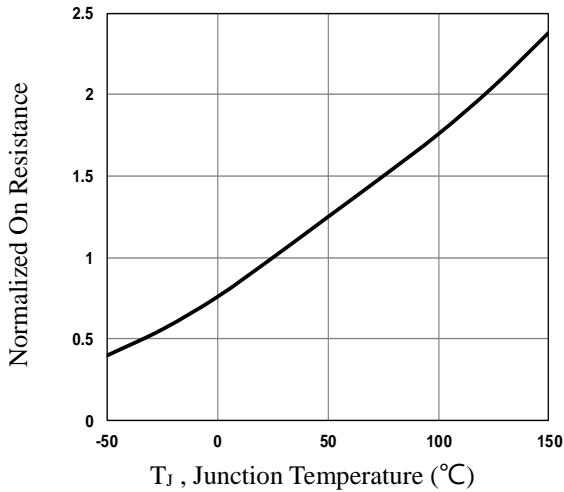
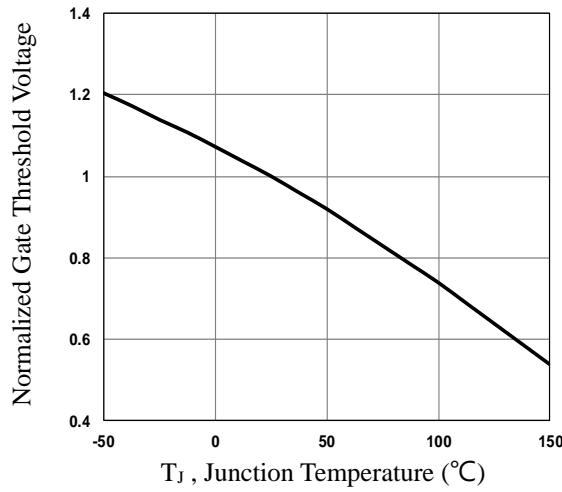
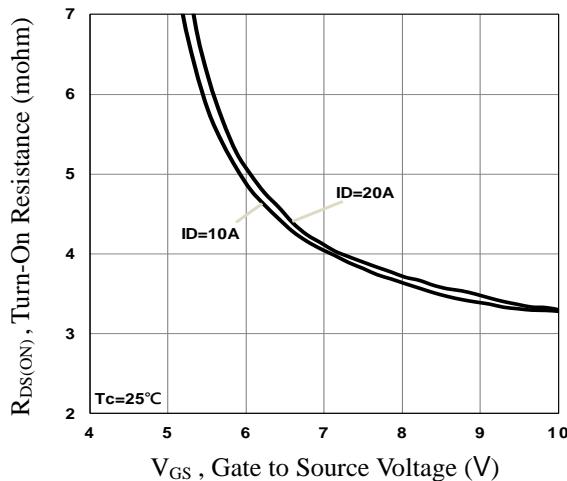
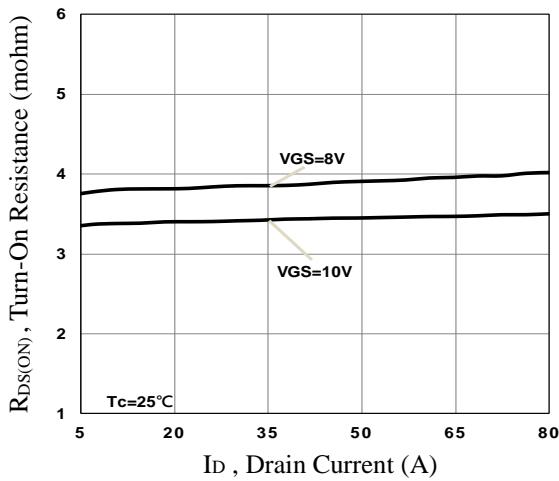
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=60\text{A}$	---	95.5	143	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	23.5	35	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	32	48	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=40\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=6\Omega$ $I_{\text{D}}=60\text{A}$	---	22	33	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	15	23	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	40	60	
$T_f$	Fall Time <sup>3, 4</sup>		---	19	29	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	5510	8265	pF
$C_{\text{oss}}$	Output Capacitance		---	1200	1800	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	70	100	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.5	---	$\Omega$

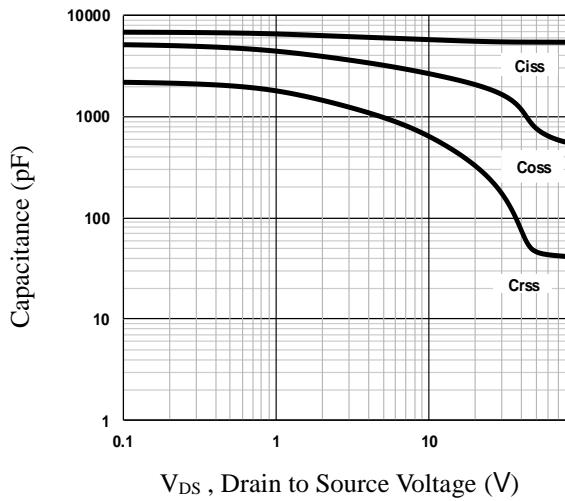
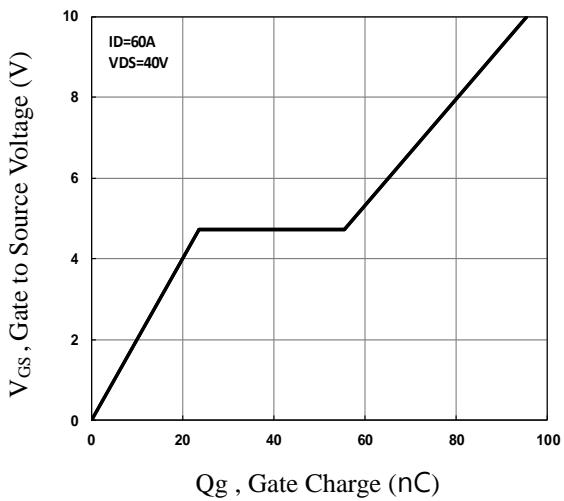
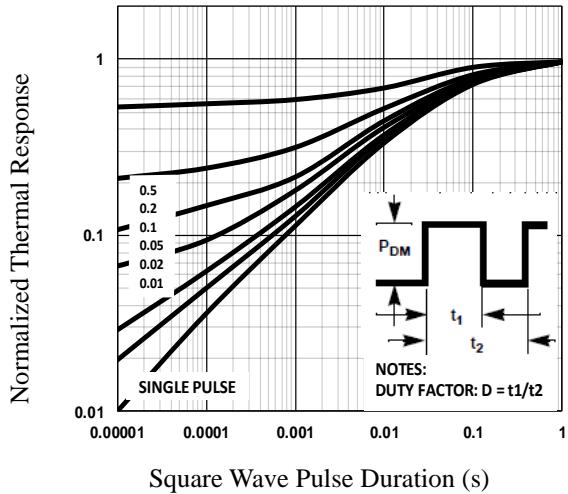
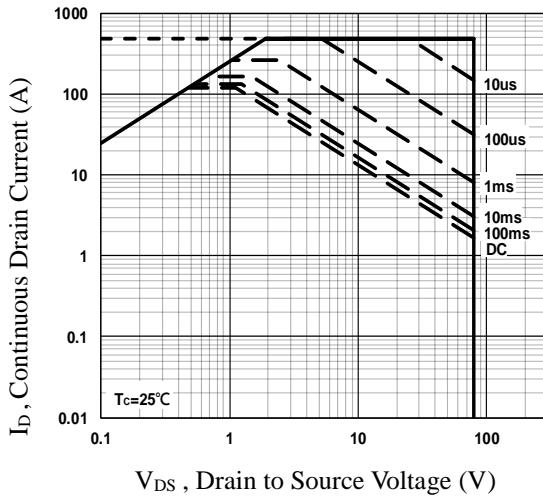
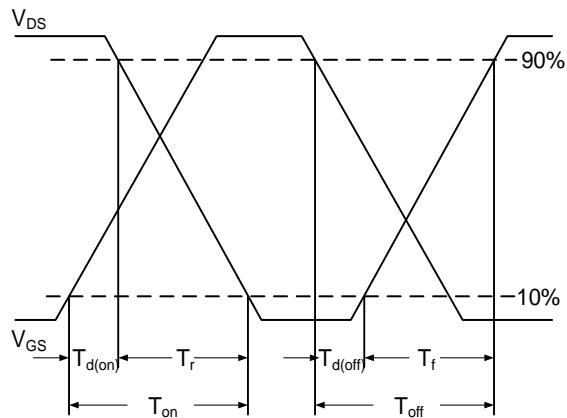
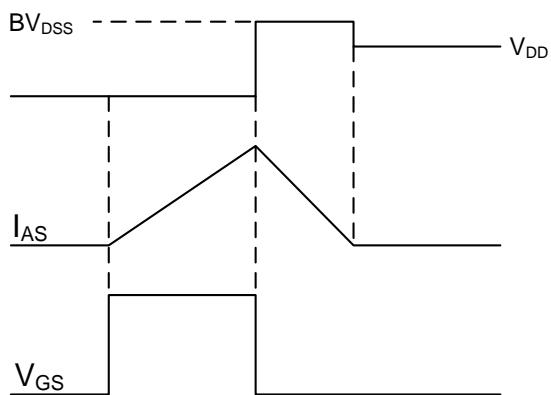
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	120	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	240	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_R=50\text{V}$ , $I_s=10\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	65	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	130	---	nC

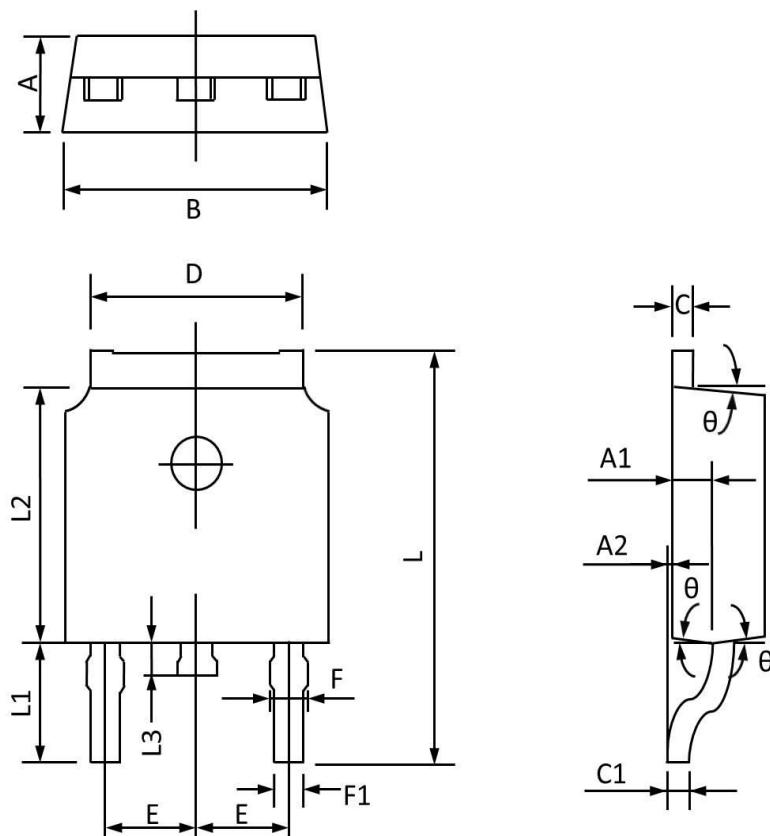
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=90\text{A}$ ,  $R_{\text{G}}=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Typical Output Characteristics**

**Fig.2 Continuous Drain Current vs.  $T_c$** 

**Fig.3 Normalized  $R_{DSON}$  vs.  $T_j$** 

**Fig.4 Normalized  $V_{th}$  vs.  $T_j$** 

**Fig.5 Turn-On Resistance vs.  $V_{GS}$** 

**Fig.6 Turn-On Resistance vs.  $I_D$**


**Fig.7 Capacitance Characteristics**

**Fig.8 Gate Charge Characteristics**

**Fig.9 Normalized Transient Impedance**

**Fig.10 Maximum Safe Operation Area**

**Fig.11 Switching Time Waveform**

**Fig.12 EAS Waveform**

## TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.450	2.150	0.096	0.085
A1	1.200	0.910	0.047	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.300	0.268	0.248
C	0.580	0.350	0.023	0.014
C1	0.550	0.380	0.022	0.015
D	5.500	5.100	0.217	0.201
E	2.390	2.000	0.094	0.079
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.300	0.244	0.209
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°